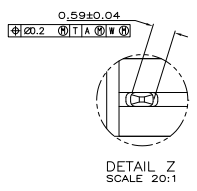
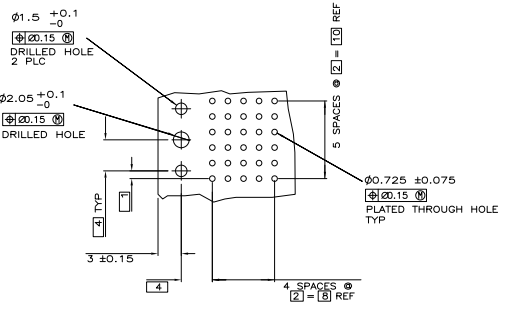
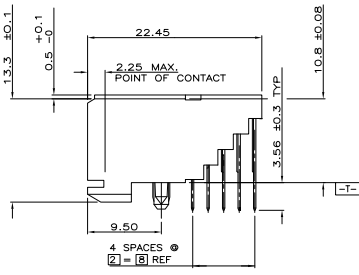
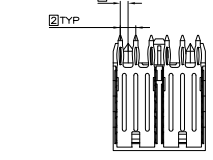
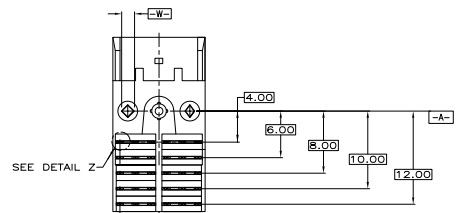
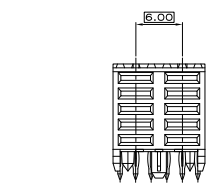
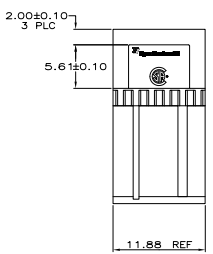


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| REV. NO. | | DESCRIPTION | DATE | BY | APP'D |
|----------|----|---------------------------|---------|----|-------|
| AD | 00 | | | | |
| | 01 | REVISED PER ECO-08-009182 | 22APR08 | DH | AS |



RECOMMENDED CIRCUIT PATTERN
 PER IPC-D300 TYPE II, CLASS C
 (COMPONENT SIDE)

- △ HOUSINGS MATERIAL: LIQUID CRYSTAL POLYMER.
- △ CONTACT MATERIAL: COPPER ALLOY
- △ CONTACT FINISH:(D)
 UNDERPLATE (ENTIRE CONTACT):
 0.00127 MIN NICKEL PER SAE-AMS-QQ-N-290
 ON MATING SURFACES:
 FLASH GOLD PER ASTM B 488, OVER
 0.00076 MIN PALLADIUM-NICKEL OVER UNDERPLATE, OR
 0.00076 MIN GOLD PER ASTM B 488 OVER UNDERPLATE.
 ON LEADS:
 0.00127 MIN MATTE TIN PER ASTM B 545 OVER UNDERPLATE.
 LUBRICATION (MIN MATING SURFACES):
 SURFACE CONDITIONER AFTER PLATING.

| | | |
|------------|----|-------------|
| FINISH | 10 | 5536649-1 |
| NO OF POSN | | PART NUMBER |

| | | | |
|--|-------------|---------------------|------------------|
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| CUSTOMER DRAWING | | DATE: 2-18-08 | BY: SHEFF |
| SIZE: A1 | DATE: 00779 | DRAWN BY: G=5536649 | REWORKED TO: --- |
| SHEET: 4.1 | | TOTAL: 1 | OF: 01 |